

POLISHING APPARATUS AND METHOD OF BONDING AND REMOVING
EXPENDABLE REPLACEMENT COMPONENTS THEREOF

ABSTRACT OF THE DISCLOSURE

A polishing apparatus includes a top ring for holding
5 a substrate and a polishing table having a polishing
surface. The substrate held by the top ring is brought
into contact with the polishing surface, and in this state,
the polishing table and the substrate are moved relative to
each other to thereby polish the substrate. Expendable
10 replacement components to be bonded to the top ring and the
polishing table, such as a backing film, a pressure ring
and a polishing cloth, are bonded in such a manner that
pieces of heat-sensitive adhesive tape are interposed
between the expendable replacement components on the one
15 hand and the top ring and the polishing table on the other.
The heat-sensitive adhesive tape is switchable between a
non-adhesive state and a adhesive state according to
whether the temperature thereof is higher or lower than a
predetermined set temperature. Thus, the expendable
20 replacement components can be bonded and removed extremely
easily by the temperature control of the heat-sensitive
adhesive tape.